



产品承认书

SPECIFICATION FOR APPROVAL

CUSTOMER:

CUSTOMER P/N:

P/N.:

HSW-H1219SP V2

DESCRIPTION:

10/100 BASE-T MAGNETICS MODULES

REF NO:

REV/NO:

A/2

DATE:

2014年9月15日首版, 2022年6月23日 更新胶壳,
使用华升微3号啤机7#模

ATTACHMENT:

■ SPECIFICATION

■ SAMPLE Q'TY OF SAMPLES _____ PCS

	√	CUSTOMER'S SIGNATURE	REMARK
FULL APPROVED			
CONDITIONAL APPROVED			
REJECTED			



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RoHS
Compliant

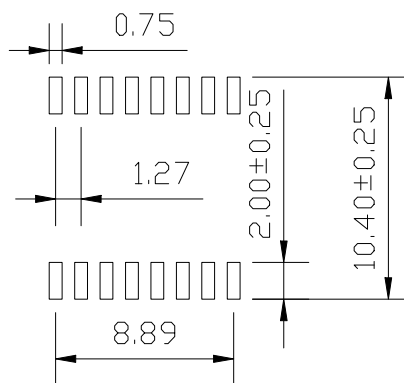
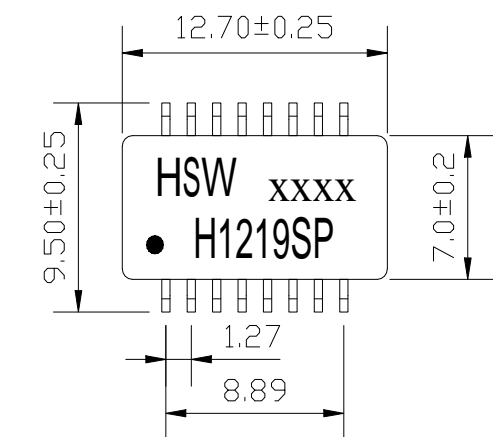




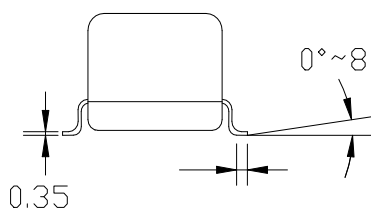
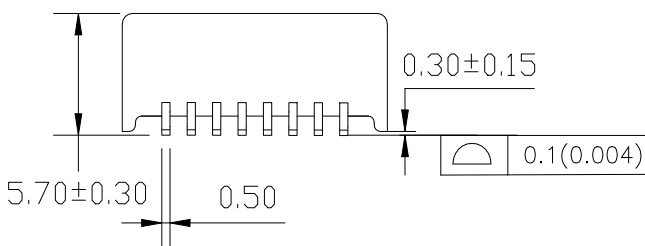
1. FEATURES:

- 1.1 Compatible with various 10/100 Base-TX transceiver requiring 1:1 transmit and 1:1 receive turns ratio.
- 1.2 Compliant with IEEE 802.3 standard including baseline wander compensation specification of 350μH OCL when Biased at 8mA
- 1.3 Low profile Surface Mount Packaging designed for Hi-Temp Reflow Process
- 1.4 Single channel interface for 10/100Mbps Ethernet applications with CMC's tuned to Enhance EMC system performance
- 1.5 Support POE 700mA Cable interface for isolation and low common mode emissions
- 1.6 Operating Temperature range: -40°C TO +70°C
- 1.7 Storage temperature range: -25°C TO +125°C

2. DIMENSIONS & MARKING



Recommended Land Pattern

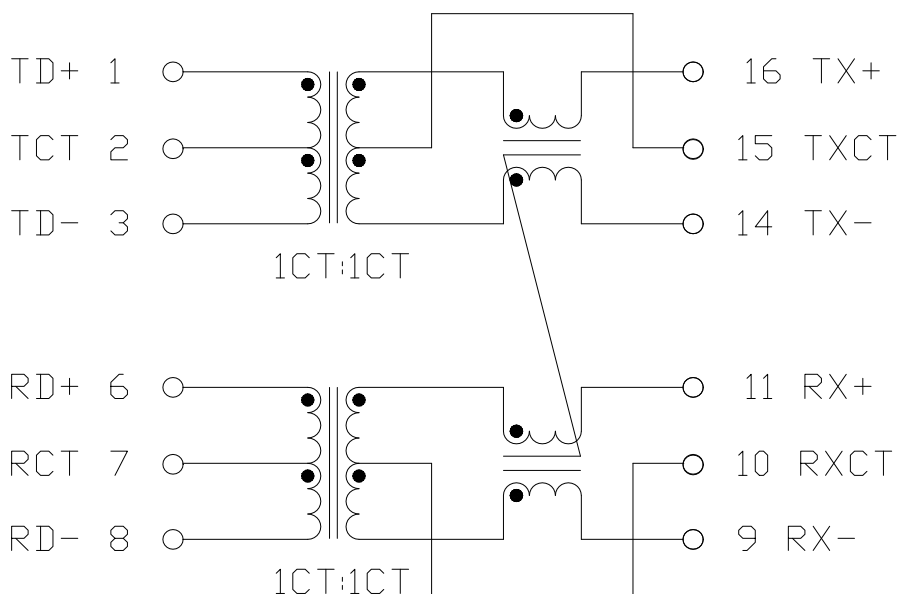


Note: 1、Dimension: mm

2、Unless otherwise specified,all tolerances are: ±0.05mm

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3. SCHEMATICS:



4. ELECTRICAL SPECIFICATIONS @25°C

4.1 OCL : 350 μ H Min. @ 100 KHz, 100mV with 8mA DC Bias

4.2 Leakage Inductance: 0.5 μ H Max. @ 100KHz, 0.2V

4.3 Cw/w: 28 pF Max. @ 100KHz, 0.2V

4.4 DCR: 1.20 Ω Max.

4.5 Turns Ratio(\pm 5%): 1CT:1CT(TX), 1CT:1CT(RX)

4.6 Polarity: 1-16, 6-11 In-Phase

4.7 Insertion Loss: -1.1 dB Max. @ 1-100MHz

4.8 Return Loss: -16 dB Min. @ 1-30MHz

-12 dB Min. @ 30-60 MHz

-10 dB Min. @ 60-80 MHz

4.9 Cross Talk: -42 dB Min. @ 1-60 MHz

-35 dB Min. @ 60-100 MHz

4.10 Common Mode Rejection : -40 dB Min. @ 1-30 MHz

-35 dB Min. @ 60 MHz

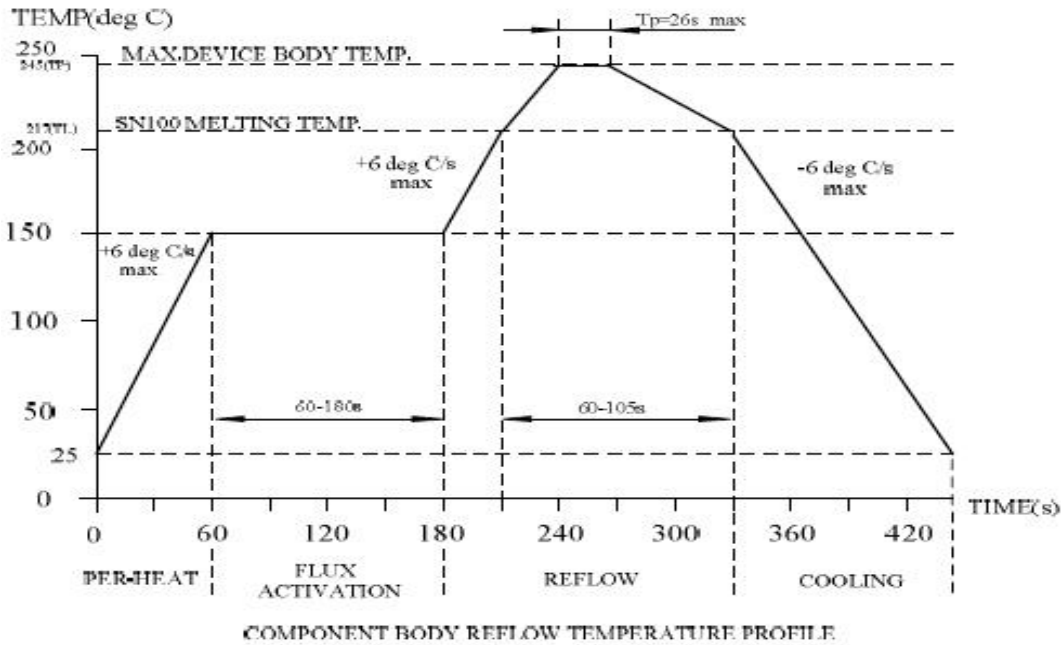
-30 dB Min. @ 80-100 MHz

4.11 Isolation HI-POT: 1500Vrms 1mA 1Second

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5. Recommended Lead Free IR Reflow Soldering Curve:



Item	Soldertechnique simulation	Temperature (°C)	Time(s)	Temperature ramp/immersion and emersion rate
1	Solder iron	350±10 (solder irno temp)	4~5	
2	Vapor phase reflow	215±5 (vapor temp)	60±5	
3	IR/convection reflow	255±5 (component temp)	30±5	1°C/s~4°C/s time above 183°C 90s~120s

Note: The curve includes recommended value only, please adjust your equipment to make sure the solder process. Details please refers to the standard J-STD-020.

6. Reliability Test Criteria:

- 6.1 Terminal strength: Pull test withstand 9.8N 60+/-0.5S no looseness or movement.
- 6.2 Solderbility: Dipped in 245°C+/-5°C molten solder for 3+/-0.5 seconds,95% min shall be smooth any and bright.
- 6.3 Resistance to soldering heat : Convection reflow condition setting: peak temperature at 260°C+0/-5°C above 217°C for 90-180 seconds, ramp-up rate 2-3°C/s. Ramp-down rate 6°C/s Max. No mechanical problem found. No electrical failure found per our specification.
- 6.4 Vibration: 1.5mm amplitude total excursion 10-55-10 Hz traversed in 1minute, x.y.z, axis for 2 hours. Shall not be any abnormality.
- 6.5 Random drop (Packing condition): Height 60cm, 3 times on the wood floorboard ,shall not be any abnormality.
- 6.6 Dry heat: 100+/-2°C 96 hours.
- 6.7 Cold: -20+/-2°C 96 hours.
- 6.8 Damp Heat: 60+/-2°C , 93+/-3% RH 96 hours.
- 6.9 Change of temperature: exposed 5 cycle; each consisting of 30 minutes at -20+/-2°C ,2-3minutes at 20+/-2°C,30 minutes at 85+/-2°C , 2-3 minutes at 20+/-2°C.

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